

3.0x2.0mm SURFACE MOUNT LED

LAMP

PRELIMINARY SPEC

Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.



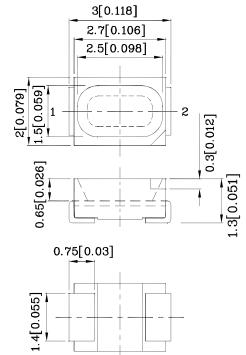




ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.



	3[0.118]			
	2.7[0.106]			
	2.5[0.098]			
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· [일당]	\// ~	0.3[0.012]		
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23		0.3		
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		÷		
0.75[0.03]			
026				
.4[0.055]				
7. — —				

Absolute Maximum Rating (TA=25°C)	FWS (InGaN)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA
Power Dissipation	PD	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	C

Operating Characteristic (TA=25°C)	FWS (InGaN)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	3.3	V
Forward Voltage (Max.) (IF=20mA)	VF	4	V
Reverse Current (Max.) (V _R =5V)	IR	10	uA
Chromaticity Coordinates	X	0.31	
(Typ.)	Y	0.31	
Capacitance (Typ.) (VF=0V, f=1MHz)	С	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Viewing Angle 2 0 1/2
				min.	typ.	
XZFWS105S	White	InGaN	Water Clear	1200	1690	125°

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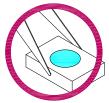


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

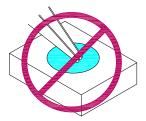
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

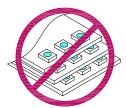


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

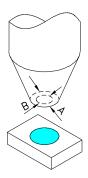




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



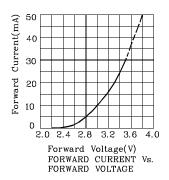
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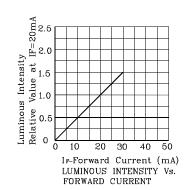


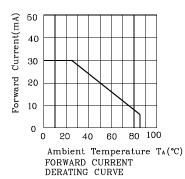
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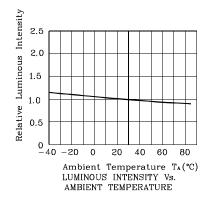
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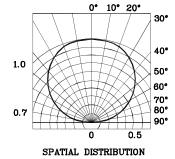
❖ FWS











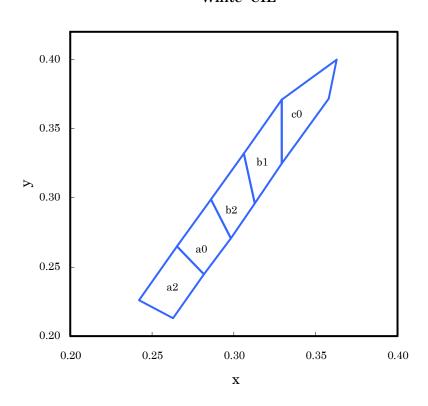
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	X	у		x	У		X	у
	0.263	0.213	a0	0.282	0.245		0.298	0.271
a2	0.282	0.245		0.298	0.271	b2	0.313	0.296
az	0.265	0.265	ao	0.286	0.299	02	0.306	0.332
	0.242	0.226		0.265	0.265		0.286	0.299
	0.313	0.296	c0	0.329	0.325			
b1	0.329	0.325		0.358	0.372			
DI .	0.329	0.371	00	0.363	0.400			
	0.306	0.332		0.329	0.371			

Published Date: NOV 30, 2009 Drawing No: XDSB3907 V1 Checked: B.L.LIU P.4/6

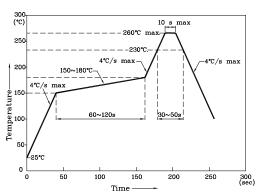


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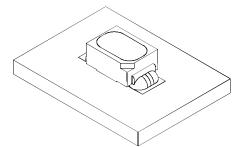
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

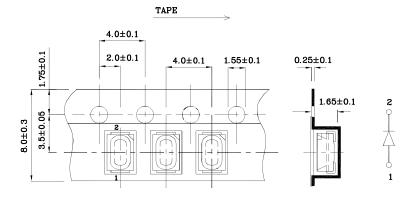


NOTES:

- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- Do not put stress to the epoxy resin during high temperatures conditions.
- ❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)
- ❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or chromaticity), the typical accuracy of the sorting process is as follows:

- 1. Measurement tolerance of the chromaticity coordinates is ± 0.01 .
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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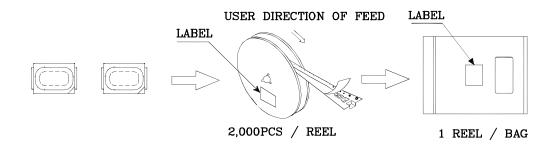


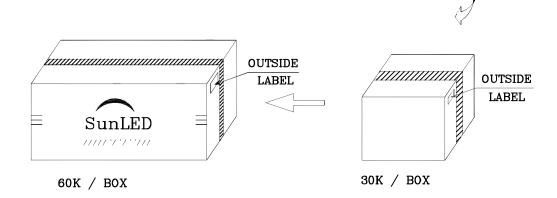
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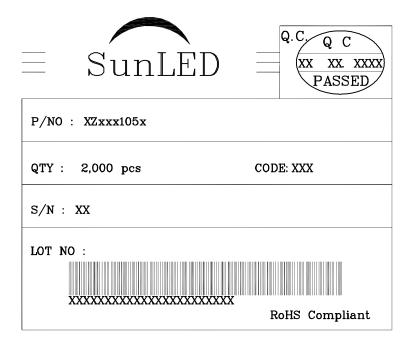
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PACKING & LABEL SPECIFICATIONS

XZFWS105S







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